

Features

Collector Current: I_C=-0.6A

• Power Dissipation of 300mw



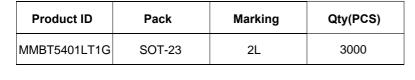
2. E

2. EMITTER

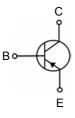
1. BASE

3. COLLECTOR

SOT-23



Package Marking and Ordering Information



Maximum Ratings (Ta=25°C uless otherwise noted)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	-160	V
Collector-Emitter Voltage	V _{CEO}	-150	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current	I _C	-600	mA
Collector Power Dissipation	P _C	300	mW
Thermal Resistance From Junction To Ambient	R _{⊝JA}	416	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T_{stg}	-55∼+150	°C

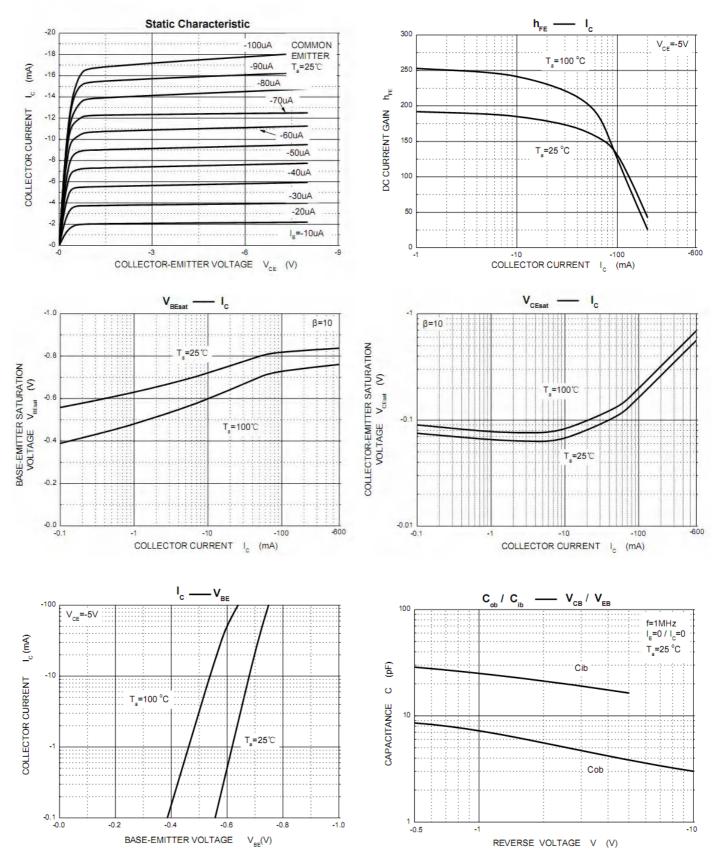
Electrical Characteristics(Ta=25°C unless otherwise specified)

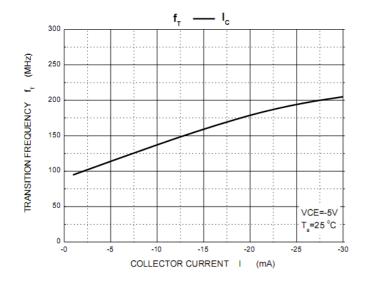
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =-100μA, I _E =0	-160			V
Collector-emitter breakdown voltage	V _{(BR)CEO} *	I _C =-1mA, I _B =0	-150			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	I _E =-10μA, I _C =0	-5			>
Collector cut-off current	I _{CBO}	V _{CB} =-120V, I _E =0			-0.1	μΑ
Emitter cut-off current	I _{EBO}	V _{EB} =-4V, I _C =0			-0.1	μA
DC current gain	h _{FE(1)} *	V _{CE} =-5V, I _C =-1mA	80			
	h _{FE(2)} *	V _{CE} =-5V, I _C =-10mA	100		300	
	h _{FE(3)} *	V _{CE} =-5V, I _C =-50mA	50			
Collector-emitter saturation voltage	V _{CE(sat)1} *	I _C =-10mA, I _B =-1mA			-0.2	V
	V _{CE(sat)2} *	I _C =-50mA, I _B = -5mA			-0.5	V
Base-emitter saturation voltage	V _{BE(sat)1} *	I _C =-10mA, I _B =-1mA			-1	٧
	V _{BE(sat)2} *	I _C =-50mA, I _B =-5mA			-1	V
Transition frequency	f _T	V _{CE} =-5V,I _C =-10mA, f=30MHz	100			MHz

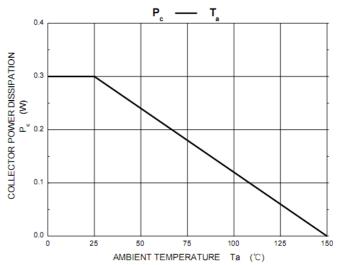
^{*}Pulse test: pulse width ≤300µs, duty cycle≤ 2.0%.



Typical Characteristics

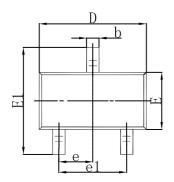


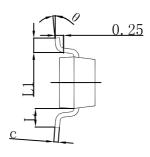


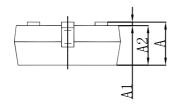




SOT-23 Package Outline Dimensions

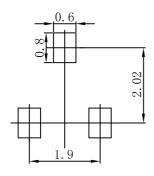






Cumbal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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